

Title (en)  
CONTACT ARRANGEMENT, ELECTRONICS ASSEMBLY COMPRISING THE CONTACT ARRANGEMENT AND METHOD FOR FORMING THE CONTACT ARRANGEMENT

Title (de)  
KONTAKTANORDNUNG, ELEKTRONIKBAUGRUPPE UMFASSEND DIE KONTAKTANORDNUNG UND VERFAHREN ZUR AUSBILDUNG DER KONTAKTANORDNUNG

Title (fr)  
SYSTÈME DE CONTACT, MODULE ÉLECTRONIQUE COMPORTANT LE SYSTÈME DE CONTACT ET PROCÉDÉ DE CRÉATION DU SYSTÈME DE CONTACT

Publication  
**EP 3794639 A1 20210324 (DE)**

Application  
**EP 19724407 A 20190510**

Priority  
• DE 102018207537 A 20180515  
• EP 2019062063 W 20190510

Abstract (en)  
[origin: WO2019219533A1] The invention relates to a composite assembly (1) of three stacked joining partners (10, 20, 30) and a corresponding method for joining a layered stack consisting of three joining partners (10, 20, 30). The three stacked joining partners (10, 20, 30) are integrally bonded by a top soulder layer (3) and a bottom soulder layer (5), a top joining partner (10) and a bottom joining partner (30) being arranged at a fixed height, at a predetermined distance (H) from each other, the top soulder layer (3) consisting of a first soulder with a first melting temperature between the top joining partner (10) and a central joining partner (20), and the second soulder layer (5) consisting of a second soulder with a higher, second melting temperature between the central joining partner (20) and the bottom joining partner (30), and the top joining partner (10) comprising a soulder compensating opening (14) filled with the first soulder and open at the top, from which the first soulder flows into the gap between the top joining partner (10) and the central joining partner (20) in order to fill the gap.

IPC 8 full level  
**H01L 23/492** (2006.01); **H01L 21/60** (2006.01); **H01L 23/488** (2006.01)

CPC (source: EP US)  
**B23K 1/0016** (2013.01 - US); **H01L 21/4882** (2013.01 - US); **H01L 23/367** (2013.01 - US); **H01L 23/3735** (2013.01 - US); **H01L 23/4922** (2013.01 - US); **H01L 24/32** (2013.01 - EP); **H01L 24/33** (2013.01 - EP); **H01L 24/37** (2013.01 - EP); **H01L 24/40** (2013.01 - EP); **H01L 24/83** (2013.01 - EP); **H01L 24/84** (2013.01 - EP); **H01L 24/92** (2013.01 - EP); **B23K 2101/40** (2018.08 - US); **H01L 23/49513** (2013.01 - US); **H01L 24/75** (2013.01 - EP); **H01L 24/77** (2013.01 - EP); **H01L 24/81** (2013.01 - US); **H01L 2224/26175** (2013.01 - EP); **H01L 2224/2732** (2013.01 - EP); **H01L 2224/291** (2013.01 - EP); **H01L 2224/29294** (2013.01 - EP); **H01L 2224/293** (2013.01 - EP); **H01L 2224/32013** (2013.01 - EP); **H01L 2224/32245** (2013.01 - EP); **H01L 2224/33181** (2013.01 - EP); **H01L 2224/37011** (2013.01 - EP); **H01L 2224/37013** (2013.01 - EP); **H01L 2224/40499** (2013.01 - EP); **H01L 2224/40996** (2013.01 - EP); **H01L 2224/75703** (2013.01 - EP); **H01L 2224/75704** (2013.01 - EP); **H01L 2224/75705** (2013.01 - EP); **H01L 2224/75754** (2013.01 - EP); **H01L 2224/75755** (2013.01 - EP); **H01L 2224/75756** (2013.01 - EP); **H01L 2224/77703** (2013.01 - EP); **H01L 2224/83143** (2013.01 - EP); **H01L 2224/83191** (2013.01 - EP); **H01L 2224/83192** (2013.01 - EP); **H01L 2224/83193** (2013.01 - EP); **H01L 2224/83815** (2013.01 - EP); **H01L 2224/84815** (2013.01 - EP); **H01L 2224/9221** (2013.01 - EP)

C-Set (source: EP)  
1. **H01L 2224/291 + H01L 2924/014**  
2. **H01L 2224/293 + H01L 2924/014**  
3. **H01L 2224/29294 + H01L 2924/00014**  
4. **H01L 2224/2732 + H01L 2924/00014**  
5. **H01L 2224/40499 + H01L 2924/014**  
6. **H01L 2224/9221 + H01L 2224/83 + H01L 2224/84**

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
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